

Part Number: XZM2ACR60W

3.0mmx1.5mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Features

- \bullet 3.0mmx1.5mm SMT LED,1.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- \bullet Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

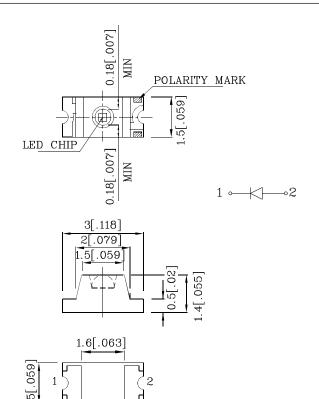




Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.20(0.008") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Rating (TA=25°C)	M2ACR (AlInGaP)	Unit	
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA
Power Dissipation	Рт	84	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	30

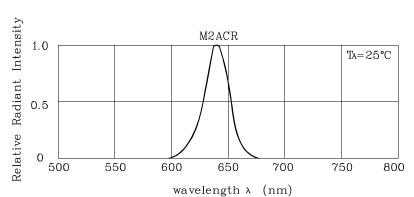


Operating Characteristic (TA=25°C)	M2ACR (AlInGaP)	Unit	
Forward Voltage (Typ.) (IF=20mA)	VF	2.2	V
Forward Voltage (Max.) (IF=20mA)	VF	2.8	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	640	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	630	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	25	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	27	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZM2ACR60W	Red	AlInGaP	Water Clear	1500	2690	640	70°
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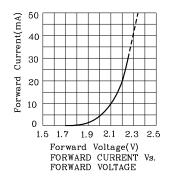
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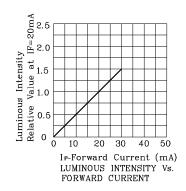


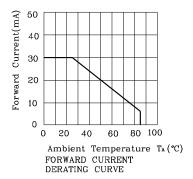


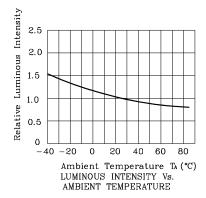
RELATIVE INTENSITY Vs. WAVELENGTH

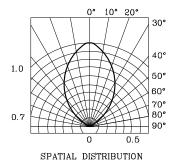
❖ M2ACR









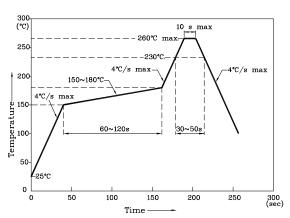


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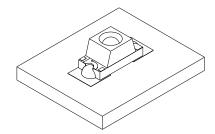
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



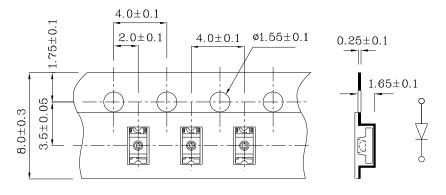
NOTES:

- 1. Maximum soldering temperature should not exceed 260°c.
- 2. Recommended reflow temperature: 145°c-260°c.
- Do not put stress to the epoxy resin during high temperatures conditions.
- **❖** Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)
 - 4.4
- ♦ The device has a single mounting surface. The device must be mounted according to the specifications.



* Tape Specification (Units:mm)

TAPE



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

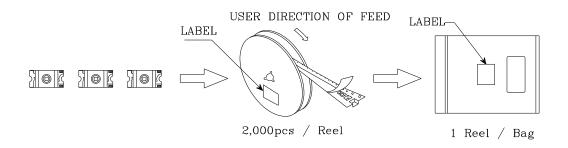


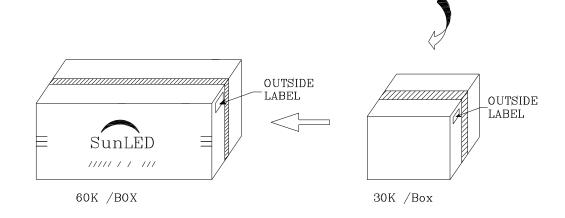
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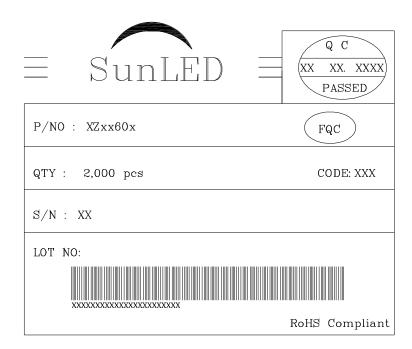
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PACKING & LABEL SPECIFICATIONS

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